N OR NS PACKAGE

SLLS152B - DECEMBER 1992 - REVISED APRIL 2003

8 NC

- Meets TIA/EIA-422-B, TIA/EIA-485-A, and CCITT Recommendations V.11 and X.27
- Low Supply-Current Requirements . . .
 30 mA Max
- Driver Output Capacity . . . ±60 mA
- Thermal Shutdown Protection
- Driver Common-Mode Output Voltage Range of -7 V to 12 V
- Receiver Input Impedance . . . 12 kΩ Min
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Input Hysteresis . . . 60 mV Typ
- Receiver Common-Mode Input Voltage Range of ±12 V
- Operates From Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection

(TOP VIEW) NC D vcc 14 RΓ 13 V_{CC} 2 RE [3 12 ∏ A DE Π 4 Пв 11 D 10 🛮 Z GND ∏ 6 9 ∏ Y

NC - No internal connection

GND [

description/ordering information

The SN75ALS181 is a differential driver and receiver pair designed for bidirectional data communication on multipoint bus transmission lines. The design provides for balanced transmission lines and meets TIA/EIA-422-B and TIA/EIA-485-A, and CCITT recommendations V.10, V.11, X.26, and X.27.

The SN75ALS181 combines a 3-state differential line driver and a differential-input line receiver that operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, that can be connected together externally to function as a direction control. The driver differential outputs and the receiver differential inputs are connected to separate pins for greater flexibility and are designed to offer minimum loading to the bus when the driver is disabled or $V_{\rm CC} = 0$. These ports feature wide positive and negative common-mode voltage changes, making the device suitable for party-line applications.

ORDERING INFORMATION

TA	T _A PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (N)	Tube of 25	SN75ALS181N	SN75ALS181N
0 0 10 70 0	SOP (NS)	Reel of 2000	SN75ALS181NSR	75ALS181

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Function Tables

EACH DRIVER

INPUT	ENABLE	OUTPUTS			
D	DE	Y	Z		
Н	Н	Н	L		
L	Н	L	Н		
Х	L	Z	Z		

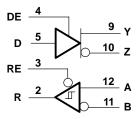
EACH RECEIVER

DIFFERENTIAL A-B	ENABLE RE	OUTPUT Y
V _{ID} ≥ 0.2 V	L	Н
$-0.2 \text{ V} < \text{V}_{1D} < 0.2 \text{ V}$	L	?
$V_{ID} \le -0.2 V$	L	L
Χ	Н	Z

H = high level, L = low level, ? = indeterminate,

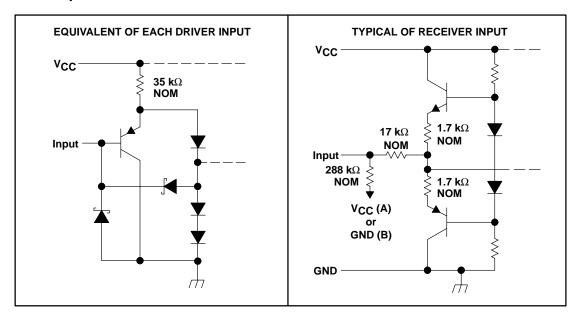
X = irrelevant, Z = high impedance (off)

logic diagram (positive logic)

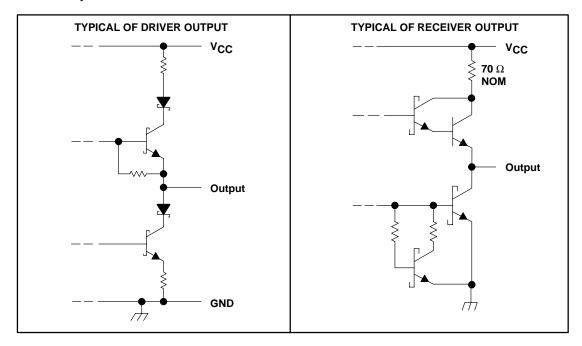




schematics of inputs



schematics of outputs



SN75ALS181 DIFFERENTIAL DRIVER AND RECEIVER PAIR

SLLS152B - DECEMBER 1992 - REVISED APRIL 2003

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage, D, DE, and RE inputs	
Output voltage range, driver	–9 V to 14 V
Input voltage range, receiver	–14 V to 14 V
Receiver differential input voltage range (see Note 2)	–14 V to 14 V
Package thermal impedance, θ _{JA} (see Notes 3 and 4): N package	80°C/W
NS package	76°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltage, are with respect to network ground terminal.
 - 2. Differential input voltage is measured at the noninverting terminal with respect to the inverting terminal.
 - 3. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

			MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.75	5	5.25	V
Voc	Common-mode output voltage (see Note 5)	ee Note 5) Driver			12	V
VIC	Common-mode input voltage (see Note 5) Receiver		-12		12	V
VIH	High-level input voltage	D, DE, and RE	2			V
V _{IL}	Low-level input voltage	D, DE, and RE			0.8	V
٧ _{ID}	Differential input voltage				±12	V
lau	High-level output current	Driver			-60	mA
ЮН	nign-level output current			-400	μΑ	
lai	Low lovel output current	Driver			60	mA
lOL	Low-level output current			8	ША	
TA	Operating free-air temperature	0		70	°C	

NOTE 5: The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this table for common-mode output voltage level only.



DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONI	DITIONS	MIN	TYP†	MAX	UNIT
VIK	Input clamp voltage	I _I = -18 mA				-1.5	V
Vo	Output voltage	IO = 0	0		6	V	
V _{OD1}	Differential output voltage	IO = 0		1.5		6	V
		V _{CC} = 5 V,		1/2 V _{OD1}			
VOD2	Differential output voltage	R _L = 100 Ω	See Figure 1	2			V
		R _L = 54 Ω		1.5	2.3	5	
VOD3	Differential output voltage	$V_{test} = -7 V to 12 V$,	See Figure 2	1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage (see Note 6)	R_L = 54 Ω or 100 Ω ,	See Figure 1			±0.2	V
Voc	Common-mode output voltage	$R_1 = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			3	٧
ΔIVOCI	Change in magnitude of common-mode	$R_{I} = 54 \Omega \text{ or } 100 \Omega,$	See Figure 1			-1 ±0.2	V
41 * 0C1	output voltage (see Note 6)	_				±0.2	•
loz	High-impedance-state output current	$V_0 = -7 \text{ V to } 12 \text{ V},$	See Note 7			±100	μΑ
lΗ	High-level input current	V _{IH} = 2.4 V			-	20	μΑ
Iμ	Low-level input current	V _{IL} = 0.4 V				-100	μΑ
		V _O = -7 V				-250	
loo	Short-circuit output current	AO = ACC				250	mA
los	Short-circuit output current	V _O = 12 V			250	IIIA	
		V _O = 0 V			-150		
loo	Supply current (total package)	No load Outputs enabled Outputs disabled			21	30	mA
Icc	Supply culterit (total package)				14	21	IIIA

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.

NOTES: 6. $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	Т	EST CONDITION	MIN	TYP [†]	MAX	UNIT	
t _{dD}	Differential output delay time, t_{dDH} or t_{dDL}	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3	9	13	20	ns
tsk(p)	Pulse skew (t _{dDH} - t _{dDL})	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3		1	8	ns
t _t	Differential output transition time	$R_L = 54 \Omega$,	$C_L = 50 pF$,	See Figure 3	3	10	16	ns
^t PZH	Output enable time to high level	$R_L = 110 \Omega$,	See Figure 4			36	53	ns
tPZL	Output enable time to low level	$R_L = 110 \Omega$,	See Figure 5			39	56	ns
^t PHZ	Output disable time from high level	$R_L = 110 \Omega$,	See Figure 4			20	31	ns
^t PLZ	Output disable time from low level	$R_L = 110 \Omega$,	See Figure 5			9	20	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.



^{7.} This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

RECEIVER SECTION

electrical characteristics over recommended ranges of supply voltage, common-mode input voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TE	ST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{T+}	Positive-going threshold voltage, differential input	V _O = 2.7 V,	$I_0 = -0.4 \text{ mA}$				0.2	V
V _T –	Negative-going threshold voltage, differential input	V _O = 0.5 V,	I _O = 8 mA		-0.2			V
V _{hys}	Input hysteresis (V _{T+} – V _{T-})					60		mV
VIK	Input clamp voltage, RE	I _I = −18 mA					-1.5	V
Vон	High-level output voltage	$V_{ID} = 200 \text{ mV},$	$I_{OH} = -400 \mu A$,	See Figure 6	2.7			V
V _{OL}	Low-level output voltage	$V_{ID} = -200 \text{ mV},$	$I_{OL} = 8 \text{ mA},$	See Figure 6			0.45	V
loz	High-impedance-state output current	V _O = 0.4 V to 2.4 V					±20	μΑ
1.	Line input compat	Other input at 0 V,	V _I = 12 V				1	mA
11	Line input current	See Note 7	V _I = -7 V			-0.8	IIIA	
lн	High-level input current, RE	V _{IH} = 2.7 V					20	μΑ
Ι _Ι L	Low-level input current, RE	V _{IL} = 0.4 V					-100	μΑ
rį	Input resistance				12			kΩ
los	Short-circuit output current	V _{ID} = 200 mV,	VO = 0 V		-15		-85	mA
laa	Supply ourrent (total package)	No lood	Outputs enabled			21	30	m A
Icc	Supply current (total package)	No load	Outputs disabled		14	21	mA	

† All typical values are at V_{CC} = 5 V and T_A = 25°C. NOTE 7: This applies for both power on and power off. Refer to TIA/EIA-485-A for exact conditions.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 15 pF (unless otherwise noted) (see Figure 7)

	PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
tPHL	Propagation delay time, high- to low-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V}$	10	16	25	ns
tPLH	Propagation delay time, low- to high-level output	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V}$	10	16	25	ns
t _{sk(p)}	Pulse skew (tpLH - tpHL)	$V_{ID} = -1.5 \text{ V to } 1.5 \text{ V}$		1	8	ns
tPZH	Output enable time to high level			7	15	ns
tPZL	Output enable time to low level			9	19	ns
^t PHZ	Output disable time from high level			18	27	ns
tPLZ	Output disable time from low level			10	15	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$ and $T_A = 25^{\circ}\text{C}$.



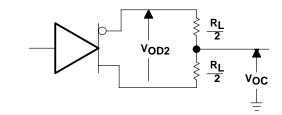


Figure 1. Driver Test Circuit, V_{OD} and V_{OC}

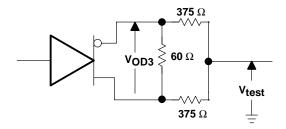
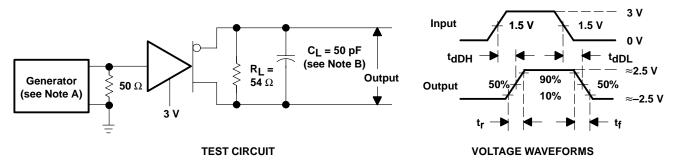


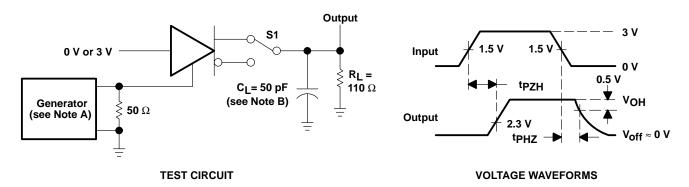
Figure 2. Driver Circuit, V_{OD3}



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 6 ns, $t_f \leq$ 7 ns, $t_f \leq$ 8 ns, $t_f \leq$ 8 ns, $t_f \leq$ 9 ns, t_f

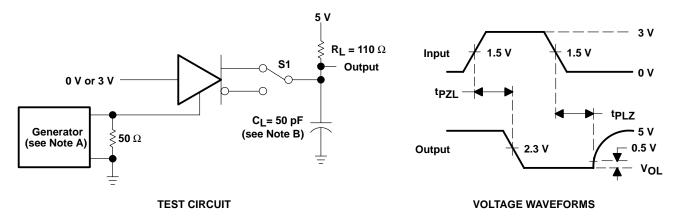
B. C_L includes probe and jig capacitance.

Figure 3. Driver Differential-Output Delay and Transition Times



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$
 - B. C_L includes probe and jig capacitance.

Figure 4. Driver Enable and Disable Times



- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 6 ns, $t_{C} \leq$ 0 ns, $t_{C} \leq$ 0 ns, $t_{C} \leq$ 1 MHz, 50% duty cycle, $t_{C} \leq$ 1 mHz, 50% duty cycle, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 2 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 2 ns, $t_{C} \leq$ 1 ns, $t_{C} \leq$ 2 ns, $t_{C} \leq$ 3 ns, $t_{C} \leq$ 3 ns, $t_{C} \leq$ 3 ns, $t_{C} \leq$ 4 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 6 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 5 ns, $t_{C} \leq$ 6 ns, $t_{C} \leq$ 7 ns, $t_{C} \leq$ 8 ns, $t_{C} \leq$ 9 ns,
 - B. C_L includes probe and jig capacitance.

Figure 5. Driver Enable and Disable Times

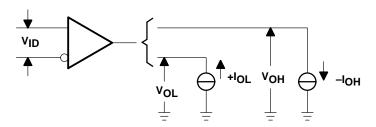
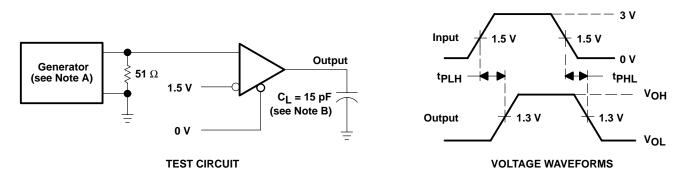


Figure 6. Receiver, VOH and VOL

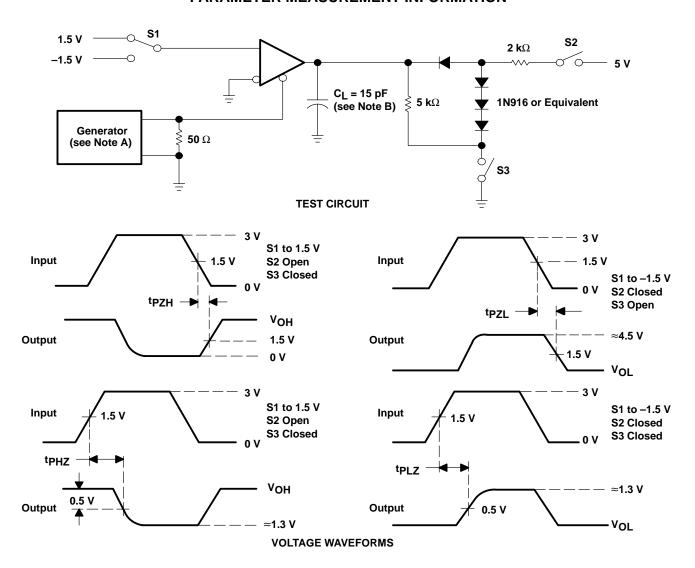




NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. CL includes probe and jig capacitance.

Figure 7. Receiver Propagation-Delay Times



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 6 ns, $t_{\Gamma} \leq$ 7 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 8 ns, $t_{\Gamma} \leq$ 9 ns, $t_$

B. C_L includes probe and jig capacitance.

Figure 8. Receiver Output Enable and Disable Times





com 18-Jul-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS181N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS181NSLE	OBSOLETE	SO	NS	14		TBD	Call TI	Call TI
SN75ALS181NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS181NSRG4	ACTIVE	SO	NS	14	2000 (Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

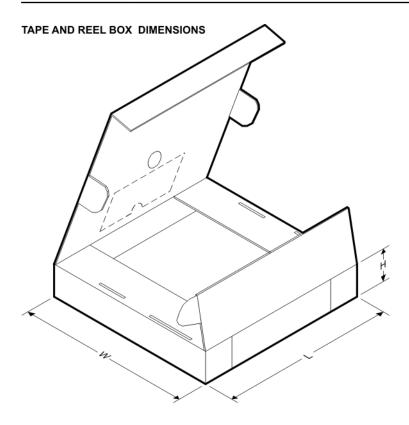
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS181NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS181NSR	SO	NS	14	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated